

APPARATUS FOR EDGE POLISHING UNIFORMITY CONTROL

ABSTRACT OF THE DISCLOSURE

An invention is provided for a platen for use in a CMP system. The platen
5 includes an inner set of pressure sub regions capable of providing pressure to a polishing
pad disposed above the platen. Each of the inner pressure sub regions is disposed below
a wafer and within a circumference of the wafer. In addition, the platen includes an outer
set of pressure sub regions capable of providing pressure to a polishing pad. Each of the
outer set of pressure sub regions is disposed below the wafer and outside the
10 circumference of the wafer. In this manner, the outer set of pressure sub regions is
capable of shaping the polishing pad to achieve a particular removal rate.